



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



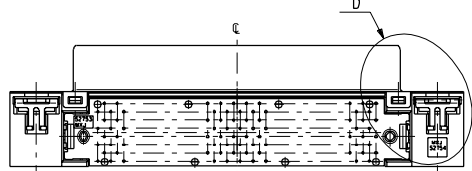
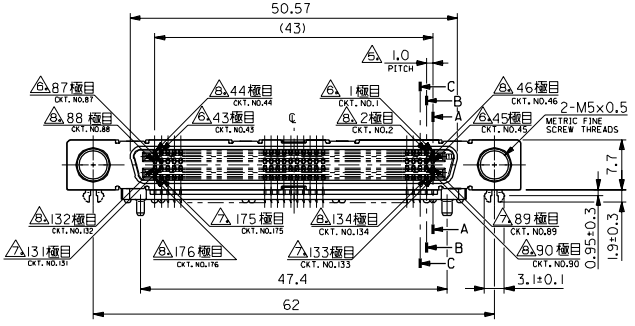
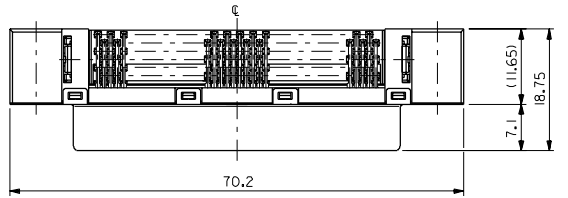
Contact us

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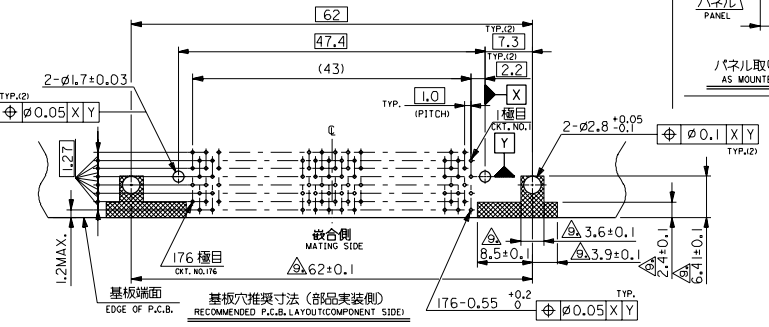
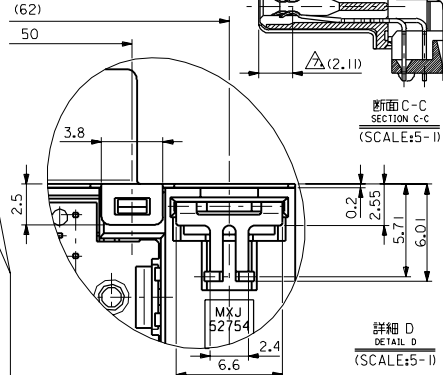
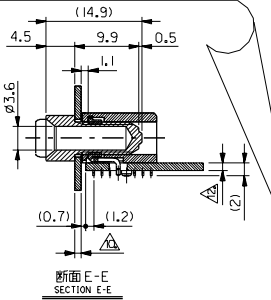
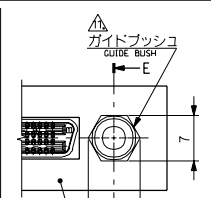
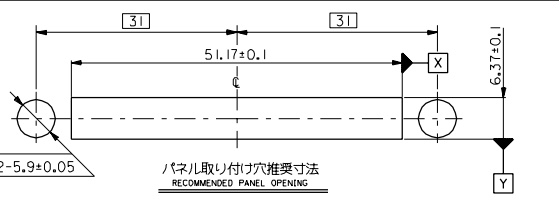
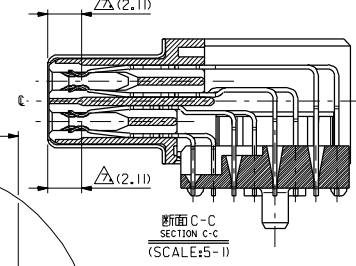
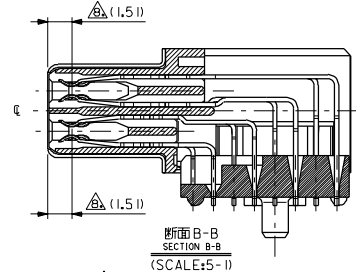
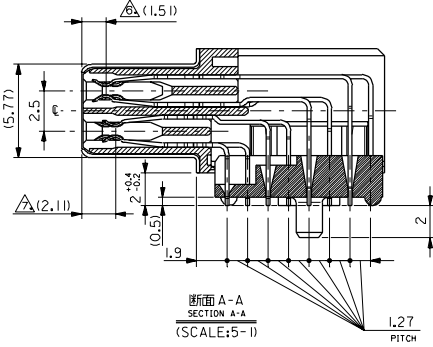
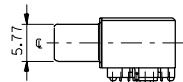
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





- 注) L 材質 MATERIAL
- ハウジング : ガラス入り耐熱樹脂、白色、UL94V-0
 - ハウジング : G.F.HEAT RESISTANT PLASTIC, WHITE, UL94V-0
 - ガイドプレート : ガラス入り耐熱樹脂、白色、UL94V-0
 - ガイドプレート : G.F.HEAT RESISTANT PLASTIC, WHITE, UL94V-0
 - ターミナル : リン青銅
 - ターミナル : PHOSPHOR BRONZE
 - シールドカバー : 鋼材
 - シールドカバー : STEEL
 - メタルペグ : 鋼材
 - メタルペグ : STEEL
2. ターミナル メッキ仕様 TERMINAL PLATING
- 金メッキ : 0.76 μm MIN. (接点部)
 - 金メッキ : GOLD (CONTACT AREA)
 - 半田メッキ : 1.0 μm MIN. (半田付け部)
 - 半田メッキ : TIN-LEAD (SOLDER AREA)
 - ニッケルメッキ : 2.0 μm MIN. (下地メッキ)
 - ニッケルメッキ : NICKEL (UNDER PLATING)
3. シールド メッキ仕様 SHIELD COVER PLATING
- ニッケルメッキ : 2.0 μm MIN.
 - ニッケルメッキ : NICKEL

4. メタルペグ メッキ仕様 METAL PEG PLATING
- メタルペグ : 鋼材
 - メタルペグ : STEEL
 - 半田メッキ : 1.0 μm MIN.
 - 半田メッキ : TIN-LEAD
- △ 公差非累積 TOLERANCES NON CUMULATIVE
- △ 1, 43, 45, 87 極目に適用。 APPLIES TO CIRCUIT NUMBERS 1, 43, 45, 87.
 - △ 奇数極に適用。但し、1, 43, 45, 87 極目を除く。 APPLIES TO ODD CIRCUITS EXCEPT CIRCUIT NUMBERS 1, 43, 45, 87.
 - △ 偶数極に適用。 APPLIES TO EVEN CIRCUIT NUMBERS
 - △ パターン禁止エリア (2ヶ所) NO FOOT PRINT TO BE DRAWN IN THESE TWO AREAS.
 - △ 取り付けパネル厚さ 0.4~1.0 mm RECOMMENDED PANEL THICKNESS (SOLDER AREA)
 - △ パネル取り付け専用パーツ型番 : 58001-0000 PART NUMBER OF PANEL MOUNTING FASTENER : 58001-0000
 - △ (詳細はモレックス図番 SD-58001-0000 を参照下さい。) REFER TO THE DRAWING NO. SD-58001-0000 ON DETAILS.
 - △ 取り付け基板厚さ 0.8 ~ 1.4mm RECOMMENDED P.C.B. THICKNESS



材料 MATERIAL	注参照 SEE NOTES	モレックス MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社
体上り FINISH	注参照 SEE NOTES	REVISION ONLY ON CAD SYSTEM
適用電線規格 WIRE RANGE	---	TITLE 名称
被覆径 INS. RANGE	---	1.0mm 1/0 DOCKING CONN. REC. ASSY (GUIDE BUSH TYPE)
角度 ANGLE	13°	角 度
30 以上	40.3	30 以上
10 以上 30 未満	40.25	10 以上 30 未満
10 未満	40.2	10 未満
公差 TOLERANCES	0	新開封 RELEASED (TS055) MS
検査記録 RECORD	---	検査記録 RECORD
品質管理 QUALITY CONTROL	---	品質管理 QUALITY CONTROL
製図者 DRAWN BY	CHK'D BY	製図者 DRAWN BY
検査者 CHECKED BY	承認者 APPROVED BY	検査者 CHECKED BY
縮尺 SCALE	2-1	縮尺 SCALE
DWG. NO.	SD-52755-1760	REV
		0